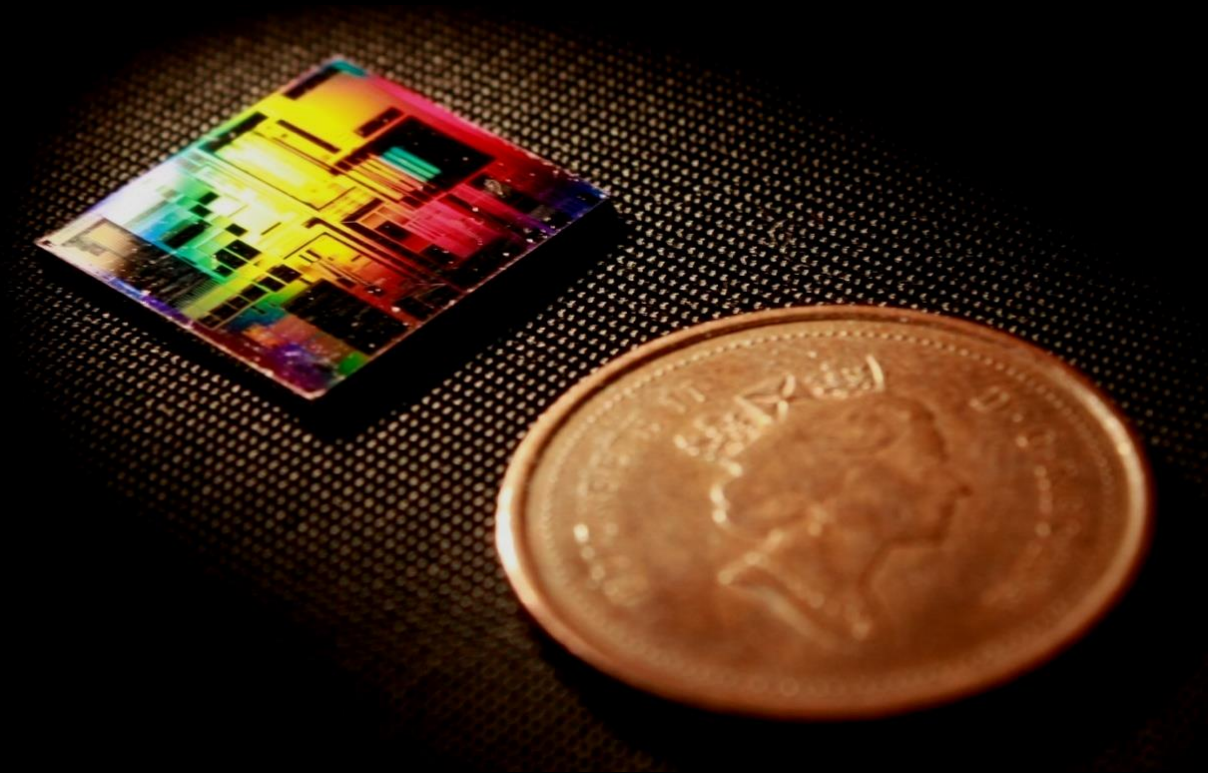


Designing and Planning Layouts

2019 SiEPIC Passive Silicon Photonics Workshop, Vancouver, Canada



Mustafa Hammood,
The University of British Columbia, Vancouver, Canada



a place of mind
THE UNIVERSITY OF BRITISH COLUMBIA

MiNa Microsystems and
Nanotechnology Group
Photonics Research Group



Electrical and
Computer
Engineering

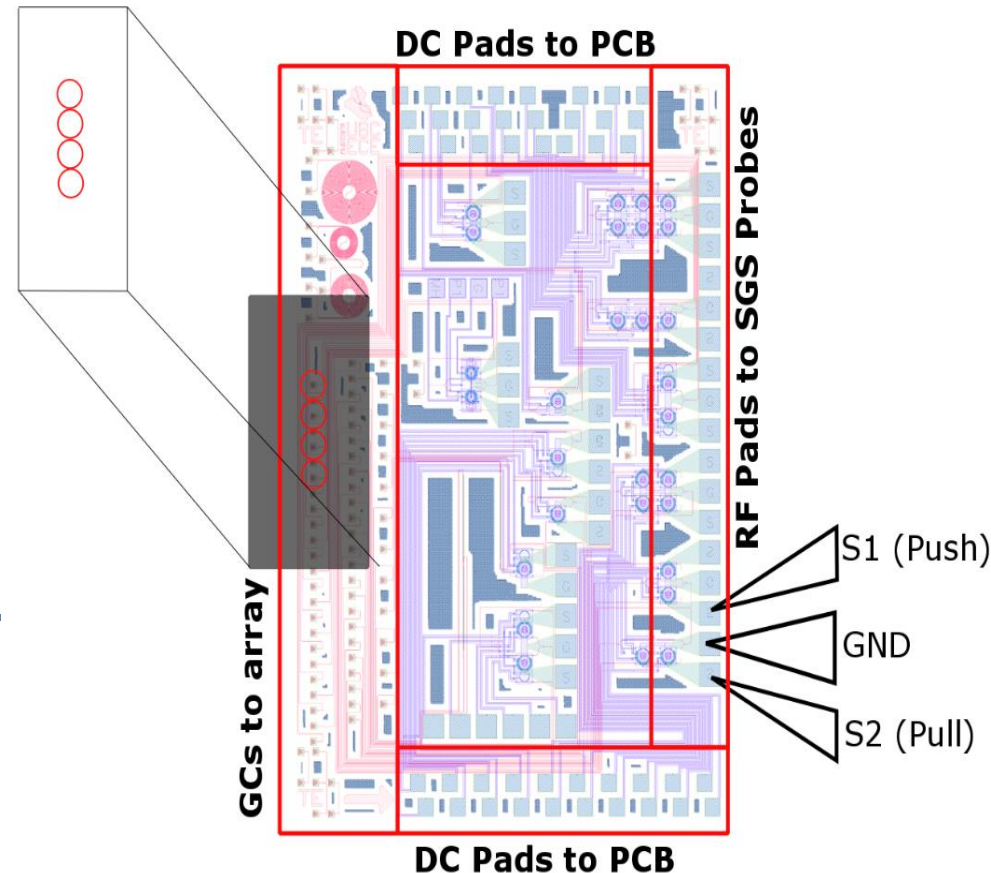
Keep your layout hierarchal

- Don't flatten your layout (or at least save the flattened as a separate version)
- Maintains your Pcell properties

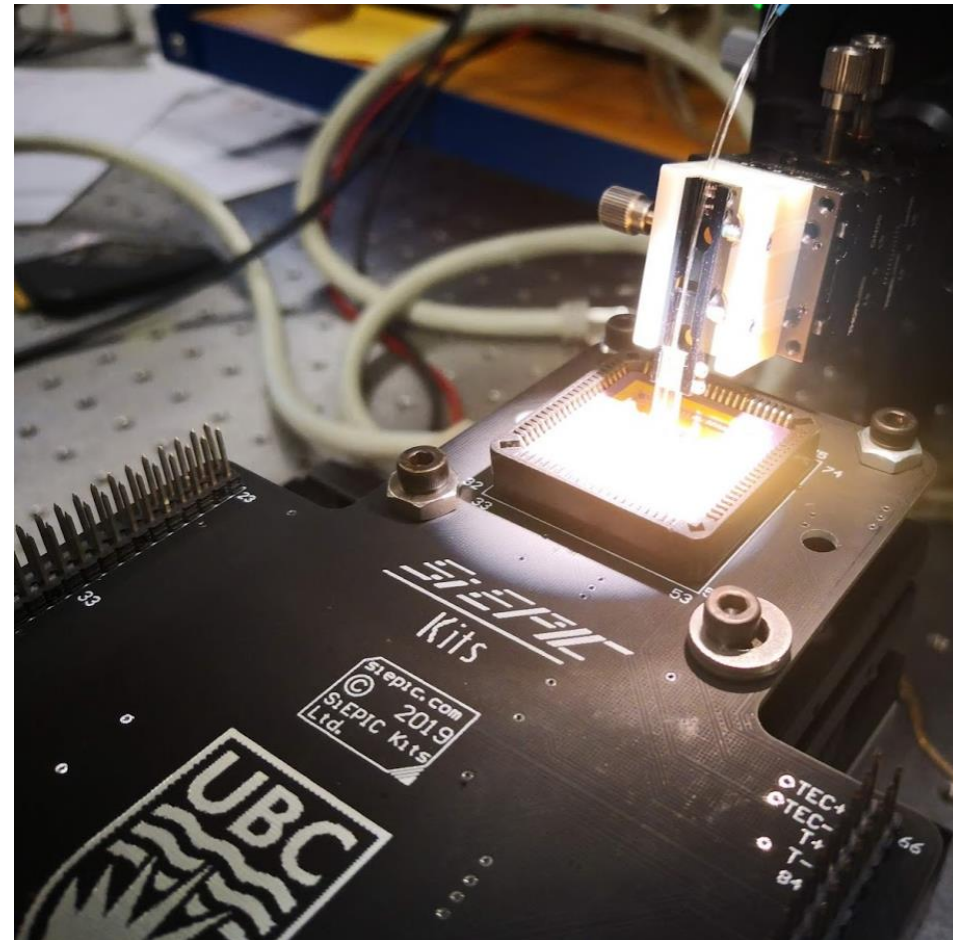
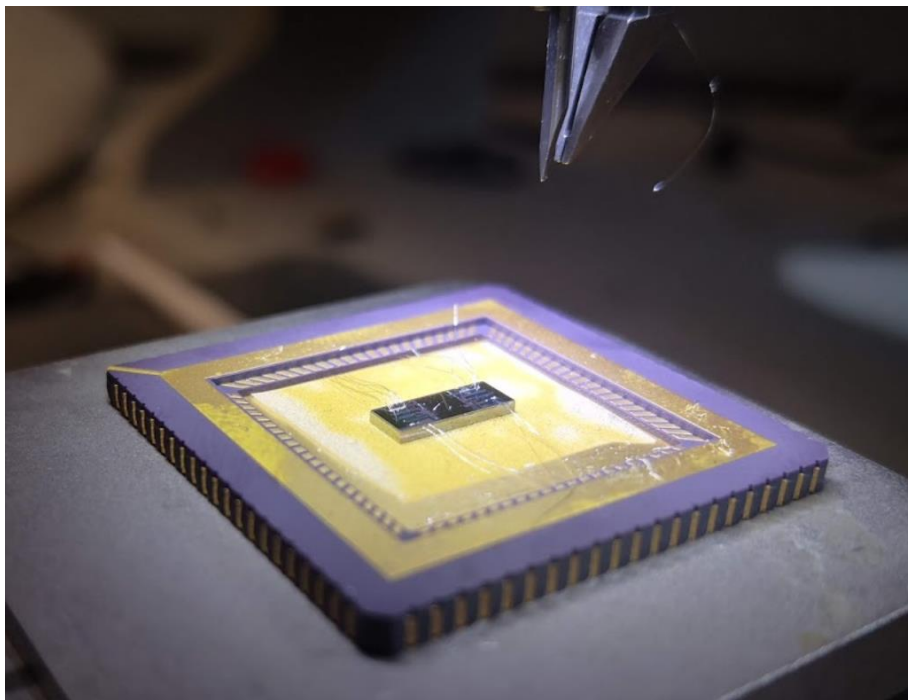


Design for testing

- Think of all the off-chip interfaces
 - Optical fiber array(s)
 - DC Probing needles
 - DC wire bonds
- RF Probing
 - Microwave traces
 - Impedance matching
 - On-chip termination?
 - Sheet resistance /sq.
 - Which probe are you using?
 - Pad pitch
 - GS/GSG (single drive)
 - SGS/ GSGSG (push-pull)



Design for packaging



Alignment

- Alignment and automated testing is not easy, unless you design for it
- Keep all your GCs in the same orientation

